

- Exceptional adhesion to all commonly used base materials
- Unique organic binder system ensures reliable, highly conductive deposit
- Wide operating window for the temperature of the colloid
- Simple installation in existing process lines
- Process is complexing agent free resulting in simple waste water treatment
- No post treatment required to reduce deposit thickness or stabilize conductive layer
- Short process sequence with reduced water consumption
- Simple process control and replenishment
- Extremely economical process

"Spirit Circuits are pleased to announce the successful installation of ViaKing chemistry at its Waterlooville factory. With support from BLT Circuit Services and J-Kem and no modifications to the equipment, we had a seamless installation with minimal down time for production.

Steve Driver commented that our production team are delighted with this installation. Our diverse range of PCBs include mixed substrates and bonded ceramic boards, these are all being processed with a single pass. Extensive testing and microsections have been performed and we are delighted with the results.

During the installation we also processed PTH flex and flex rigid multilayers with 0.2mm holes. The coverage was perfect and again this was single pass processing. We have now therefore commissioned a second line at our Lyncolec factory in Poole.

Currently we are challenging all processes and costs in the business. These installations represent a significant saving for the business."

Steve Driver
Managing Director
Spirit Circuits Limited



ISO 9001:2008
APPROVED

Introducing the latest in
direct metallisation

J-Kem ViaKing

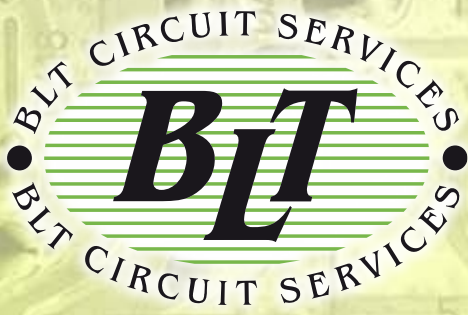
A new generation Carbon/Graphite colloidal process for
direct metallisation of printed circuit boards.

Horizontal Process Flow

Step	Process	Concentration	Time	Temp.	Comments
1	Conditioner DS280	6% 280-M 1.2% 280-R	10-30 sec	60-65°C	Flooded module
2	Cascade rinse	-	30 sec	-	-
3	ViaKing Conductivator 202-E	35% 202-E	30-40 sec	15-33°C	Flooded module continuous filtration
4	Dryer	-	-	80°C	-
5	Micro Etch Copperwet 1195	5-10% 1195 plus 2% Sulphuric Acid	30 sec	RT	Adjust to give 0.25- 0.35 micron etch
6	Cascade rinse	-	30 sec	-	-
7	Anti Tarnish PAT790*	5% PAT790	30 sec	RT	Spray or flood *Optional process
8	Rinse	-	15 sec	-	-
9	Final Dry	-	-	-	-



Conditioner DS280 and Conductivator 202-E
are supplied in 25L containers.



J-Kem ViaKing

A new generation Carbon/Graphite colloidal process for direct metallisation of printed circuit boards.

Process Control



Conditioner DS280

Add 15ml DS280R and 60ml DS280M per 10m² processed. Maintain bath level with de-mineralised water and change bath monthly to ensure optimum performance.

ViaKing Conductivator 202-E

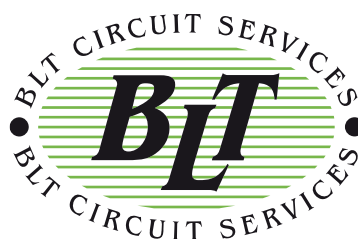
Maintain pH between 9.0 and 10.7 and check solids content by evaporation. Maintain solids content at 2.9% to 3.5%. BLT will monitor the solids content for customers.

1 litre of Conductivator 202-E can process 100 to 120m² of drilled panels.

Microetch 1195

Check etch rate regularly. Replenish for drag out with 10% Microetch 1195 solution and change solution when copper level reaches 15gpl.

BLT offer customers detailed Surface Topography Analysis using Hommel Etamic W10 equipment.



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